


Update: 11/05/2010	Technical Data Sheet	
Ref. : wire	<b><u>Lead Free Solder wire "Sn99.3Cu0.7"</u></b>	
Created date: 03/05/2001	<b><u>Incorporated flux HC3</u></b>	

**1 - GENERAL CHARACTERISTICS :**

A high quality binary alloy for mechanical or electrical applications which demand lead free solders on difficult-to-solder surfaces composed of tin and copper it is an efficient suitable alternative to Tin/Lead. Others benefits are increased joint strength. It highly recommended removing residues after soldering.

**ADDITIONAL INFORMATION:**

Our manufacturing processes have been subjected to FMECA analysis (equivalent of AMDEC in Europe).

**2 - CHEMICAL CHARACTERISTICS :**

2.1 Tin-Copper binary Alloy.

Amount of Tin : 99.3%

Amount of Copper : 0.7%

2.2 Tin of first smelting, copper purity of 99.90%

2.3 Chart of maximum impurities:

Sb	Pb	Ag	Cd	Bi	Fe	Zn	Al	As	Others
0.05	0.05	0.005	0.002	0.01	0.02	0.001	0.001	0.01	0.05

2.4 Amount of flux incorporated: BS441 Grades 1, 2 or 3

BS441 Flux Grade	----- Mass of flux -----		
	Minimum	Nominal	Maximum
1	1.0 %	1.3 %	1.5 %
2	1.6 %	2.2 %	2.6 %
3	2.7 %	3.3 %	3.9 %

**3- PHYSICAL CHARACTERISTICS :**

**\*ALLOY Sn99.3Cu0.7**

- 3.1 Melting point : Eutectic 227°C
- 3.2 Specific weight : 7.3 g/cm<sup>3</sup>
- 3.3 Wire diameter : From 0.5 mm to 5 mm
- 3.4 Working temperature : 350 - 450 °C

**\*FLUX HC3**

- Halide: 6.5 %
- Residues must be cleaned after soldering

**4- PACKAGING:**

- 4.1 Supplied on green spools : 500g,1Kg, other on request.
- 4.2 Packed in cartons of : 12Kg, 24Kg.
- 4.3 Identification : Boxes and spools carry product information labels.
- 4.4 Quality assurance : A certificate of conformity can be issued for each manufactured batch if requested at the time of ordering.
- 4.5 Storage : in original packaging at room temperature for 12 months.